

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2412	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:25
L2	1539	257/706.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:27
L3	171	h01l23/495.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:27
L4	152	3 and ((lead or leadframe or (lead adj frame) or frame))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:27
L5	150	4 and (pad or base or wafer or substrate or support\$3 or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:28
L6	31	5 and ((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:33
L7	3	("6229200"   "6448643"   "6452255").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/08 19:31
L8	4720	((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:33
L9	927	((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board)).clm.	US-PGPUB	OR	ON	2006/06/08 19:34
L10	210	9 and semiconductor	US-PGPUB	OR	ON	2006/06/08 19:34
L11	32	10 and (((lead or leadframe or (lead adj frame) or frame) with (project\$4 or "X" or (X adj2 shape\$3) or cross\$4 or orthogonal\$3))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:41
L12	122	8 and (((lead or leadframe or (lead adj frame) or frame) with (project\$4 or "X" or (X adj2 shape\$3) or cross\$4 or orthogonal\$3))).clm. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:41
L13	90	12 not 11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:41
S1	7432	257/670-677,e23.031,e23.042,e23.043,e23.046,e23.047,e23.05,e23.06,e23.066.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:23

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S2	956	S1 and ((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:28
S3	597	S2 and ((lead or leadframe or (lead adj frame) or frame) with (project\$4 or "X" or (X adj2 shape\$3) or cross\$4 or orthogonal\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:35
S4	4	S3 and ("JFET" or (J adj3 (transistor or FET\$2)))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:30
S6	586	(S3 not S4) and ((lead or leadframe or (lead adj frame) or frame) with (electrical\$3 or connect\$3 or contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:35
S7	507	S6 and (@ad<"20020809" or @rlad<"20020809")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:36
S8	12	S7 and source and drain and gate	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:37
S9	58	(S7 not S8) and ((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:55
S10	101	(S7 not (S8 S9)) and ((lead or leadframe or (lead adj frame) or frame) with (fasten\$3 or strength\$4 or secur\$4 or tie\$3 or tying or clamp\$4 or bind\$4 or bound\$3 or bin\$4) with (die or chip or "IC" or device) with (pad or base or wafer or substrate or support\$3 or board)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 15:56
S11	9	("4661837"   "4721994"   "4811081"   "4812421"   "5072280"   "5101324"   "5130783"   "5138438"   "5214845").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/07 16:13
S12	26	("5294827").URPN.	USPAT	OR	ON	2006/06/07 16:16
S13	335	S7 not (S8 S9 S10 S11 S12)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 16:19
S14	221	257/676,e23.043,e23.046.ccls. and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 16:51
S15	2409	257/676.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:24
S16	2162	S15 not S3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 17:02

## EAST Search History

S18	40	S7 not (S8 S9 S10 S11 S12 S14) and (without with bond\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/08 19:25
S19	1	10/728449	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/06/07 18:41